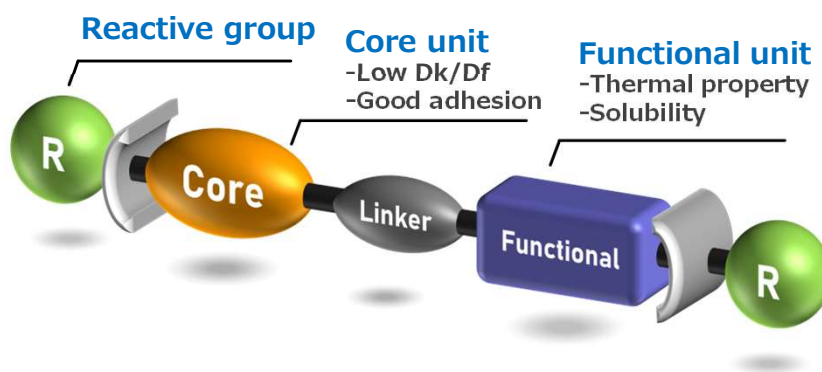


CG-7000 series

Balanced type between Df & processability

Design Concept



| | | CG-7007 | CG-7008 |
|----------------------------------------|----------------------------------------------|------------------------------------------|------------------------------------|
| Feature | | Ultra low Df High Tg Good adhesion | Ultra low Df Excellent adhesion |
| Structure | Core + Functional | Type I' | Type III' |
| | R | Radical-curable | Radical-curable |
| Product | Non-volatile (%) | 55 | 59 |
| | Solvent(%) | Toluene 45 | Toluene 41 |
| Properties | Dk/Df @10GHz | 2.6/0.0008 | 2.6/0.0009 |
| | Tg (°C, DMA) | 215 | 170 |
| Composition Initiator 0.5phr | Peel strength (N/mm, with low profile Cu) | 0.5 | 0.8 |

Curing Condition: 200°C x 2h, under N₂.